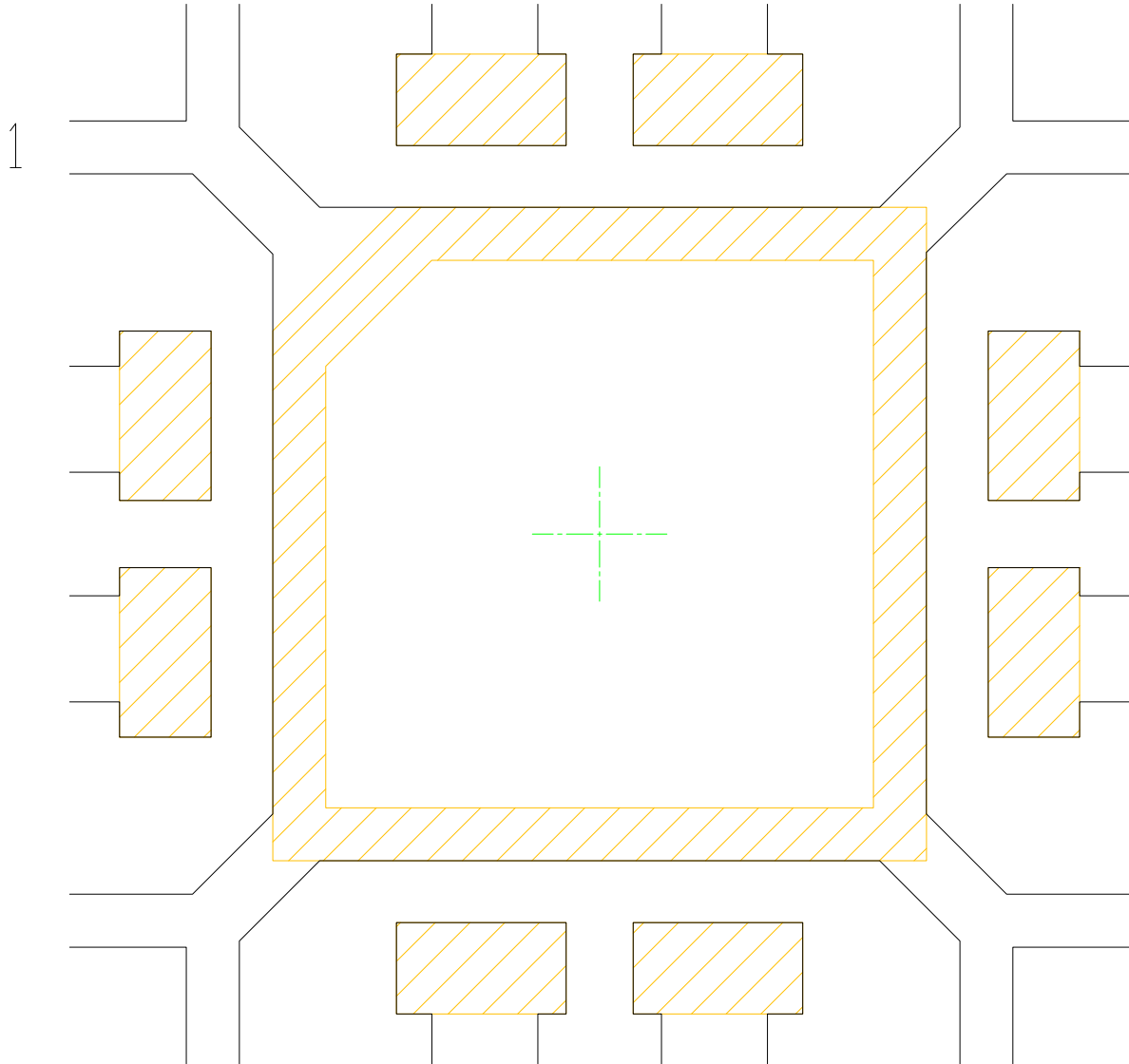



| REVISIONS | | |
|-----------|--|----------|
| REV | DESCRIPTION | DATE |
| B | ADDED EXPOSED PAD SIZE AND LEADFRAME P/N | 4-1-2016 |



 NiPdAu PLATING

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| | | | |
|-----------------------------|--------------------------------------|--|-----------------------|
| CUSTOMER: xxxxx | DOCUMENT #: |  www.promex-ind.com | |
| PROJECT NAME: xxxxx | DIE ATTACH PAD SIZE: 1.85 x 1.85 mm | | |
| DIE SIZE, mm: xxxxx | EXPOSED PAD SIZE: 1.70 x 1.70 mm | TITLE | |
| DIE THICKNESS, um: xxxxx | DAP PLATING OPTION: GROUND RING | QFN 8L 3x3 mm 0.65 PITCH BOND SHELL | |
| BOND PAD PITCH, um: xxxxx | PLATING MATERIAL: NiPdAu | LEADFRAME P/N: | REV |
| BOND PAD OPENING, um: xxxxx | LEADFRAME MATERIAL: C194 FH | 235-00049 | C |
| WIRE SIZE, um: xxxxx | LEADFRAME THICKNESS: 0.203±0.0075 mm | DO NOT SCALE | FILE NAME |
| | | | 8L-QFN-3X3-65P-BD.DWG |
| | | | SHEET |
| | | | 1 OF 1 |